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CLAIMS

- 10 1. A contact piece comprising a tungsten overlay (1) soldered onto a metallic support (3), characterized in that at least portions of the solder layer (2) and optionally the support are covered by a layer of a metal (4) which is less noble than tungsten.
- 15 2. The contact piece as claimed in claim 1, characterized in that the layer of the less noble metal is 0.1 to 20 μm thick.
3. The contact piece as claimed in claim 2, characterized in that the layer of the less noble metal is 0.2 to 2 μm thick.
- 20 4. The contact piece as claimed in claims 1 to 3, characterized in that the less noble metal is Sn, Zn, Mg or Al.
5. The contact piece as claimed in claim 4, characterized in that the less noble metal is Sn.
- 25 6. A method for the preparation of a contact piece as claimed in any one of claims 1 to 5, characterized in that a layer of a less noble metal than tungsten is applied onto the contact piece and subsequently base metal which may be present on the tungsten overlay is removed.
- 30 7. The method as claimed in claim 6, characterized in that the layer is applied via electroplating.
8. The method as claimed in claim 6 or 7, characterized in that the base metal is applied selectively onto the solder and the metallic support.

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9. The method as claimed in any one of claims 6 to 8, characterized in that the re-exposure of the tungsten overlay is carried out by sliding grinding.

10. Use of the contact piece as claimed in any one of claims 1 to 5 as a horn contact or a relay contact.